

Macronix MX25L6435E and MX25L6436E Serial Flash Comparison

1. Introduction

This application note compares the MX25L6435E and MX25L6436E 64Mb 3V serial NOR flash. The document does not provide detailed information on each individual device, but highlights the similarities and differences between them. The comparison covers the general features, performance, command sets and device ID.

In comparison with the MX25L6436E, the MX25L6435E supports new features, such as 2READ mode (1-2-2, Single I/O Command input - Dual I/O Address input - Dual I/O Data output) and 4READ mode (1-4-4, Single I/O Command input - Quad I/O Address input - Quad I/O Data output).

MX25L6435E supports a new TB (Top/Bottom) bit function, which enables Block Protection beginning at either the top or bottom of the memory array.

The MX25L6435E also has a HOLD pin added and is available in not only the 8-SOP and 16-SOP packages, but comes in a smaller 8-WSON package and a 24-TFBGA package as well.

The information provided in this document is based on datasheets listed in Section 8. Newer versions of the datasheets may override the contents of this document.

Please refer to the contents and comparison tables below for more details.



2. General Features

The MX25L6435E has a new TB (Top/Bottom) bit located in Configuration Register Bit 3. By controlling the T/B bit, memory blocks can be selected for protection beginning at either the top or bottom of the memory array.

The MX25L6435E supports two additional read modes: 2READ mode and 4READ mode. The MX25L6435E has the same or improved performance in all read modes.

The MX25L6435E also has a HOLD pin added and is available in not only the 8-SOP and 16-SOP packages, but comes in a smaller 8-WSON and 24-TFBGA packages as well. These features are summarized in Table 2-1.

Feature		MX25L6435E	MX25L6436E	
Voltage		2.7~3.6 V	2.7~3.6 V	
Interface		x1, x2, x4	x1, x2, x4	
Packages		16-SOP (300mil) 8-SOP (209mil) 8-WSON (6x5mm) 24-TFBGA (6x8mm)	16-SOP (300mil) 8-SOP (209mil) 8-WSON (8x6mm)	
Operating Tempera	iture Range	-40°C ~ +85°C	-40°C ~ +85°C	
Sector / Block		4KB / 32KB or 64KB	4KB / 32KB or 64KB	
	Fast Read (1-1-1)	104MHz	104MHz	
	Normal Read	50MHz	50MHz	
Clock Rate	DREAD (1-1-2) (Dual Output)	86MHz	70MHz	
(max.)	QREAD (1-1-4) (Quad Output)	86MHz	75MHz	
	2READ(1-2-2)	86MHz		
	4READ(1-4-4)	Up to 104MHz		
	4PP	104MHz	20MHz	
Configurable Dum	my Cycle	Yes. for 4READ mode only		
Continuous Progra	m (CP) Mode	Yes	Yes	
	Secured OTP	4Kbits	4Kbits	
Data Protection	Block Protection	BP3~BP0	BP3~BP0	
	T/B (Top/Bottom)bit	Yes		
	Individual Protection	Individual Sector/Block Protect	Individual Sector/Block Protect	
HOLD#		Yes		
SFDP		Yes	Yes	

Table 2-1: Feature Comparison





3. Performance

Both devices have similar power and timing as shown in Table 3-1.

Table 3-1: Performance Comparison

Parameter	Symbol	MX25L6435E	MX25L6436E	
Cleak Lisk / and Time	tCH	104MHz: 4.5ns 50MHz: 9ns	104MHz: 4.5ns 50MHz: 9ns	
Clock High/Low Time	tCL	104MHz: 4.5ns 50MHz: 9ns	104MHz: 4.5ns 50MHz: 9ns	
Dragram Time	Byte	12us(typ.) ; 300us(max.)	9us(typ.) ; 300us(max.)	
	Page	1.4ms(typ.); 5ms(max.)	1.4ms(typ.) ; 5ms(max.)	
	Sector	60ms(typ.) ; 300ms(max.)	60ms(typ.) ; 300ms(max.)	
Erase Time	Block	32KB:0.5s(typ.); 2s(max.) 64KB:0.7s(typ.); 2s(max.)	32KB:0.5s(typ.); 2s(max.) 64KB:0.7s(typ.); 2s(max.)	
	Chip	50s (typ.) / 80s(max.)	50s (typ.) / 80s(max.)	
CS# Active Setup Time	tSLCH	4ns(min.)	5ns(min.)	
CS# Not Active Setup Time	tSHCH	4ns(min.)	5ns(min.)	
CS# Active Hold Time	tCHSH	4ns(min.)	5ns(min.)	
CS# Not Active Hold Time	tCHSL	4ns(min.)	5ns(min.)	
CS# Deselect Time	tSHSL	Read=15ns(min.) ; Write=50ns(min.)	Read=15ns(min.) ; Write=50ns(min.)	
VCC Standby	ISB1	80uA(max.)	50uA(max.)	
Deep Power Down	ISB2	40uA(max.)	20uA(max.)	
VCC Read Current	ICC1	35mA (104MHz, 4 I/O) 25mA (86MHz, 4 I/O) 19mA (104MHz, 1 I/O) 20mA (86MHz, 2 I/O) 10mA (33MHz, 1 I/O)	22mA (75MHz, 4 I/O) 19mA (104MHz, 1 1/O) 17mA (70MHz, 2 I/O) 10mA (33MHz, 1 I/O)	
VCC Program Current	ICC2	25mA	25mA	
VCC WRSR Current	ICC3	20mA	20mA	
VCC Sector Erase Current	ICC4	25mA	25mA	
VCC Chip Erase Current	ICC5	25mA	20mA	



4. Package and Pin-out Comparison

Figure 4-1 shows the common packages and the pin-out assignments for the two devices. With the exception of the added HOLD# pin function on the MX25L6435E, both devices have the same footprint and pinout. When migrating from the 36E to the 35E, if the HOLD#/SIO3 pin is currently N/C (not connected) it can be left unconnected as the HOLD# pin is internal pull high.

Figure 4-1: Packages and Pin-outs

16-PIN SOP (300mil)								
MX25L6435E	MX25L6436E					-	MX25L6435E	MX25L6436E
HOLD#/SIO3	NC/SIO3		1	\bigcirc	16		SCLK	SCLK
VCC	VCC		2		15		SI/SIO0	SI/SIO0
NC	NC		3		14		NC	NC
NC	NC		4		13		NC	NC
NC	NC		5		12		NC	NC
NC	NC		6		11		NC	NC
CS#	CS#		7		10		GND	GND
SO/SIO1	SO/SIO1] [8		9		WP#/SIO2	WP#/SIO2

8-PIN SOP (200mil)						
MX25L6435E	MX25L6436E				MX25L6435E	MX25L6436E
CS#	CS#		1 8		VCC	VCC
SO/SIO1	SO/SIO1		2 7	· þ	HOLD#/SIO3	NC/SIO3
WP#/SIO2	WP#/SIO2		3 6		SCLK	SCLK
GND	GND		4 5		SI/SIO0	SI/SIO0

8-WSON						
MX25L6435E	MX25L6436E			MX25L6435E	MX25L6436E	
CS#	CS#		8 🗖	VCC	VCC	
SO/SIO1	SO/SIO1	2	7 🔳	HOLD#/SIO3	NC/SIO3	
WP#/SIO2	WP#/SIO2	3	6 🗖	SCLK	SCLK	
GND	GND	■ 4	5 🔳	SI/SIO0	SI/SIO0	





5. Command Set Comparison

Table 5-1 shows that the command set remain the same with the exception of the additional 2READ and 4READ (BBh and EBh, added to the 35E). The MX25L6435E does not have the Clear Security Register Fail Flags command (30h) to clear the E_FAIL or P_FAIL flags as the MX25L6436E does. The MX25L6435E clears these flags automatically at the beginning of the next command sequence.

Commar	nd	MX25L6435E	MX25L6436E
	WREN	06h	06h
Write	WRDI	04h	04h
	WRSR	01h	01h
	RDID	9Fh	9Fh
	RDSR	05h	05h
	READ	03h	03h
	RDSFDP	5A	5A
	Fast Read	0Bh	0Bh
	2READ	BBh	
Read	4READ	EBh	
	DREAD	3Bh	38h
	QREAD	6Bh	6Bh
	RES	Abh	Abh
	REMS	90h	90h
	REMS2	EFh	EFh
	REMS4	DFh	DFh
	SE	20h	20h
Гласа	RDSR READ RDSFDP Fast Read 2READ 4READ DREAD QREAD QREAD RES REMS2 REMS2 REMS4 SE BE BE32K CE 4PP PP CP RDSCUR WRSCUR ENSO EXSO ESRY DSRY DP RDP SBLK	D8h	D8h
Elase	BE32K	52h	52h
	CE	60h or C7h	60h or C7h
	4PP	38h	38h
Program	PP	02h	02h
	CP	ADh	ADh
Security Degister	RDSCUR	2Bh	2Bh
Security Register	WRSCUR	2Fh	2Fh
	ENSO	B1h	B1h
Secured OTP	EXSO	C1h	C1h
SO output	ESRY	70h	70h
	DSRY	80h	80h
Doop Dower Down	DP	B9h	B9h
	RDP	ABh	ABh
	SBLK	36h	36h
 	SBULK	READ03hRDSFDP5AFast Read0Bh2READBBh4READEBhDREAD3BhQREAD6BhREMS90hREMS2EFhREMS4DFhSE20hBED8hBE32K52hCE60h or C7h4PP38hPP02hCPADhRDSCUR2FhENSOB1hEXSOC1hESRY70hDSRY80hDPABhSBLK36hSBULK39hGBLK7EhGBULK98hCLSRRDBLOCK3Ch	39h
	GBLK	7Eh	7Eh
	GBULK	98h	98h
Clear SR	CLSR		30h
Block Protect Read	RDBLOCK	3Ch	3Ch

Table 5-1: Command Set Comparison



6. Device ID Code Comparison

Table 6-1 shows that the Manufacturer and Device IDs have not changed.

Command Type		MX25L6435E		MX25L6436E			
PDID Command	M ID	Туре	Density	M ID	Туре	Density	
RDID Command	C2	20	17	C2	20	17	
		Electronic ID		Electronic ID			
RES Command		16			16		
DEMS	M ID	Device ID		M ID	Device ID		
REMS	C2	16		C2	16		

Table 6-1: ID Code Comparison

7. Summary

The MX25L6435E is backwards compatible with most of the common commands and features of the MX25L6436E. Additionally, the supported package types have identical footprints and nearly identical pin-out definitions.

8. References

Table 8-1 shows the datasheet versions used for comparison in this application note. For the most current Macronix specification, please refer to the Macronix Website at <u>http://www.macronix.com</u>

Table 8-1: Datasheet Version

Datasheet	Location	Date Issued	Version
MX25L6435E	Macronix Website	Sep. 2012	1.0
MX25L6436E	Macronix Website	Apr. 2010	1.9



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